



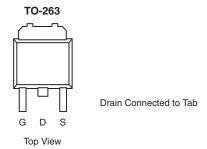
P-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A)	Q _g (Typ.)			
- 100	0.019 at V _{GS} = - 10 V	- 90	97 nC			
	0.021 at V _{GS} = - 4.5 V	- 85	97110			

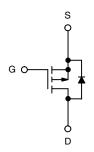
FEATURES

- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: SUM90P10-19L-E3 (Lead (Pb)-free)



P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 100	v	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		- 90		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 125 °C	I _D	- 52		
Continuodo Brain Carrent (1) = 100 O)	T _A = 25 °C	.р	- 17.2 ^{b, c}	A	
	T _A = 125 °C		- 9.9 ^{b, c}		
Pulsed Drain Current		I _{DM}	- 90	7 ^	
Continuous Source-Drain Diode Current	T _C = 25 °C		- 250		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 9 ^{b, c}	7	
Avalanche Current	L = 0.1 mH	I _{AS}	- 70		
Single-Pulse Avalanche Energy	L = 0.111111	E _{AS}	245	mJ	
	T _C = 25 °C		375		
Maximum Power Dissipation	T _C = 125 °C	P _D	125	w	
Maximum Fower Dissipation	T _A = 25 °C	' D	13.6 ^{b, c}	VV	
	T _A = 125 °C		4.5 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	8	11	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	$R_{th,IC}$	0.33	0.4	O/ VV	

Notes:

- a. Package Limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 40 $^{\circ}\text{C/W}.$

SUM90P10-19L

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SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 100			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 125		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.9			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	1	V _{DS} = - 100 V, V _{GS} = 0 V			- 1	- 1 - 500 μA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 175 °C			- 500		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = -10 \text{ V}$	- 90			Α	
		V _{GS} = - 10 V, I _D = - 20 A		0.0156	0.019	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -15 \text{ A}$		0.0173	0.021		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 20 A		80		S	
Dynamic ^b							
Input Capacitance	C _{iss}			11100			
Output Capacitance	C _{oss}	V 50 V V 0 V f 1 M l=		700		pF	
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = -50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1690			
		$V_{DS} = -50 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -90 \text{ A}$		217	326		
Total Gate Charge	Q_g			97	146	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = -50 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -90 \text{ A}$		42			
Gate-Drain Charge	Q_{gd}			51			
Gate Resistance	R_g	f = 1 MHz		3.5		Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = - 50 V, R_L = 0.56 Ω		510	855	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ - 90 A, V_{GEN} = - 10 V, R_g = 1 Ω		145	220		
Fall Time	t _f			870	1300		
Drain-Source Body Diode Characte	ristics			•		•	
Continous Source-Drain Diode Current	Is	T _C = 25 °C			- 90	A	
Pulse Diode Forward Current ^a	I _{SM}				- 250	1	
Body Diode Voltage	V _{SD}	I _S = - 20 A		- 0.8	- 1.5	V	
Body Diode Reverse Recovery Time	t _{rr}			80	120	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = -20 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		220	330	nC	
Reverse Recovery Fall Time	t _a			56			
Reverse Recovery Rise Time	t _b	7		24		ns	

Notes

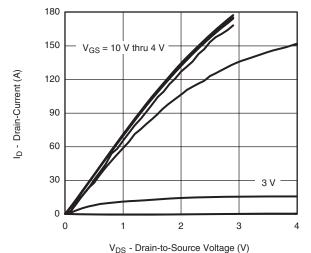
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

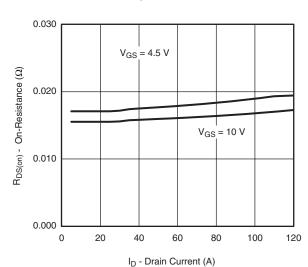


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

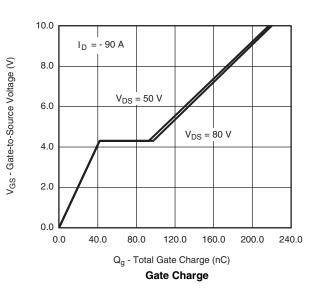


os - Diam-to-Source voltage (v)



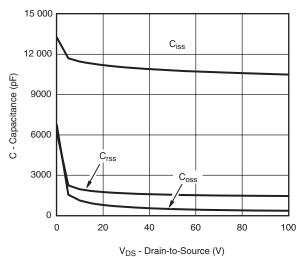


On-Resistance vs. Drain Current

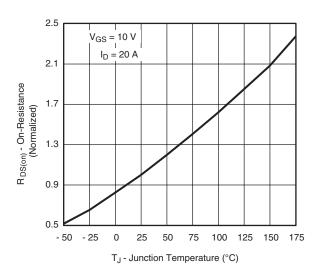


(V) 30 20 25 °C 25 °C -55 °C 0.0 1.0 2.0 3.0 4.0

V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**

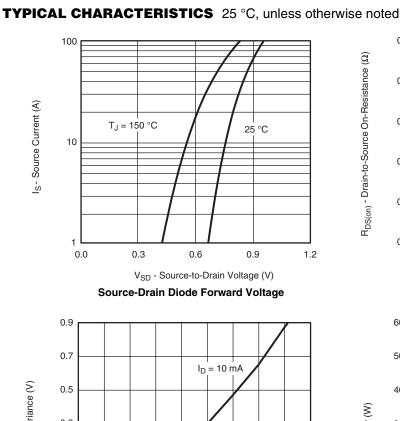


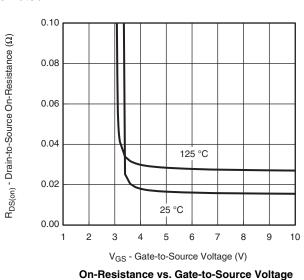
Capacitance

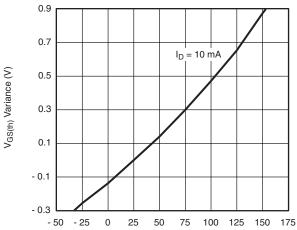


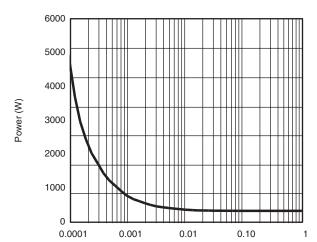
On-Resistance vs. Junction Temperature

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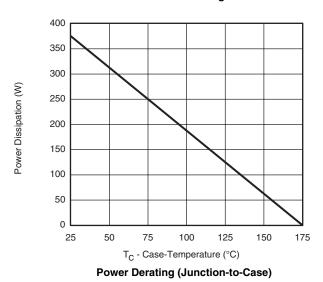


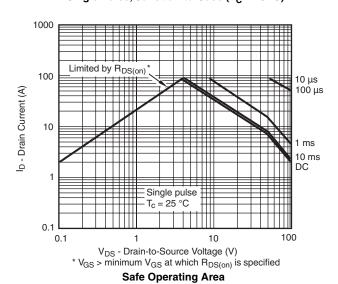




Single Pulse, Junction-to-Case (T_C = 25 °C)

Time (s)

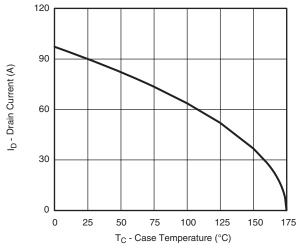


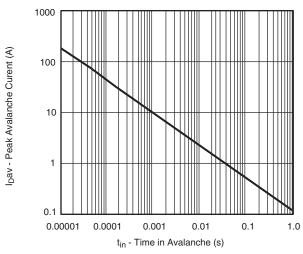




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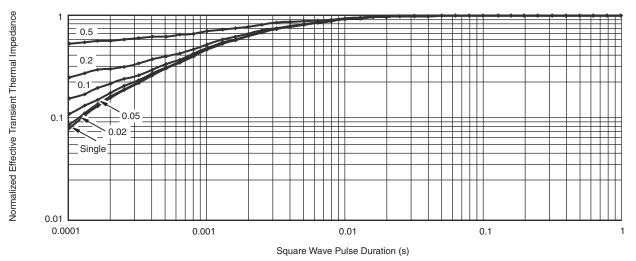
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Max Avalanche and Drain Current vs. Case Temperature



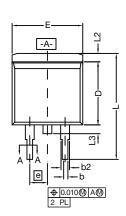


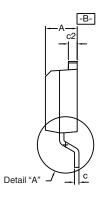
Normalized Thermal Transient Impedance, Junction-to-Case

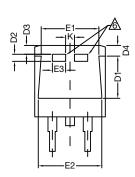
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TO-263 (D²PAK): 3-LEAD

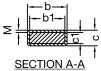








DETAIL A (ROTATED 90°)



_ - b1 , , ,	
≥ 	- -

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

6. This feature is for thick lead.

		INC	HES	MILLIMETERS		
DIM.		MIN.	MAX.	MIN.	MAX.	
Α		0.160	0.190	4.064	4.826	
b		0.020	0.039	0.508	0.990	
	b1	0.020	0.035	0.508	0.889	
	b2	0.045	0.055	1.143	1.397	
c*	Thin lead	0.013	0.018	0.330	0.457	
C	Thick lead	0.023	0.028	0.584	0.711	
c1	Thin lead	0.013	0.017	0.330	0.431	
CI	Thick lead	0.023	0.027	0.584	0.685	
	c2	0.045	0.055	1.143	1.397	
	D	0.340	0.380	8.636	9.652	
	D1	0.220	0.240	5.588	6.096	
D2		0.038	0.042	0.965	1.067	
D3		0.045	0.055	1.143	1.397	
	D4	0.044	0.052	1.118	1.321	
E		0.380	0.410	9.652	10.414	
	E1	0.245	-	6.223	=	
E2		0.355	0.375	9.017	9.525	
	E3	0.072	0.078	1.829	1.981	
е		0.100) BSC	2.54 BSC		
K		0.045	0.055	1.143	1.397	
L		0.575	0.625	14.605	15.875	
L1		0.090	0.110	2.286	2.794	
L2		0.040	0.055	1.016	1.397	
L3		0.050	0.070	1.270	1.778	
L4		0.010 BSC		0.254 BSC		
M		-	0.002	-	0.050	
ECN: T13-0707-Rev. K, 30-Sep-13						

DWG: 5843





RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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